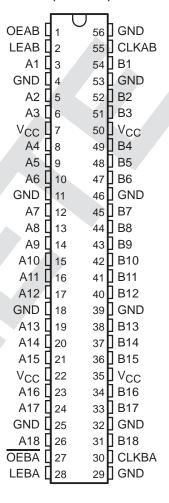
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Member of the Texas Instruments Widebus™ Family
- UBT[™] (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, or Clocked Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

The SN74ALVC16501 18-bit universal bus transceiver is designed for low-voltage (3.3-V) V_{CC} operation; it is tested at 2.5-V, 2.7-V, and 3.3-V V_{CC} .

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

DGG OR DL PACKAGE (TOP VIEW)



Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

The SN74ALVC16501 is available in Ti's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVC16501 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC, UBT, and Widebus are trademarks of Texas Instruments Incorporated.

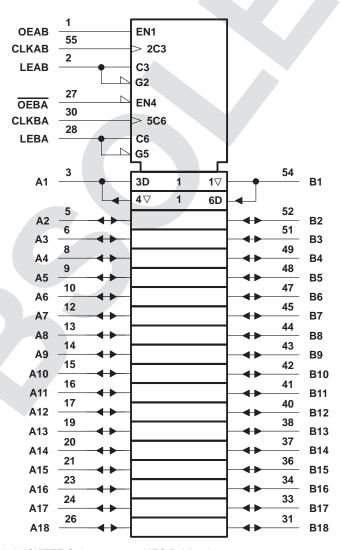
TEXAS INSTRUMENTS

FUNCTION TABLE†

	INPUTS					
OEAB	LEAB	CLKAB	Α	В		
L	Χ	Χ	Χ	Z		
Н	Н	Χ	L	L		
Н	Н	Χ	Н	Н		
Н	L	\uparrow	L	L		
Н	L	\uparrow	Н	Н		
Н	L	Н	Χ	B ₀ ‡		
Н	L	L	Χ	В ₀ §		

- † A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.
- [‡] Output level before the indicated steady-state input conditions were established, provided that CLKAB is high before LEAB goes low
- § Output level before the indicated steady-state input conditions were established

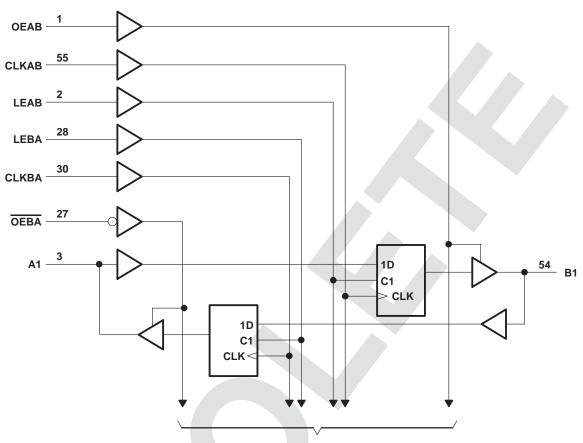
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} Input voltage range, V_{I} (except I/O ports) (see Note 1) Input voltage range, V_{I} (I/O ports) (see Notes 1 and 2) Output voltage range, V_{O} (see Notes 1 and 2) Input clamp current, I_{IK} (V_{I} < 0) Output clamp current, I_{OK} (V_{O} < 0 or V_{O} > V_{CC}) Continuous output current, I_{OK} (V_{O} = 0 to V_{CC}) Continuous current through V_{CC} or GND	$ \begin{array}{l} -0.5 \text{ V to } 4.6 \text{ V} \\ \text{to V}_{\text{CC}} + 0.5 \text{ V} \\ \text{to V}_{\text{CC}} + 0.5 \text{ V} \\ \dots -50 \text{ mA} \\ \dots \pm 50 \text{ mA} \\ \dots \pm 50 \text{ mA} \end{array} $
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



SN74ALVC16501 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS SCAS261A - JANUARY 1993 - REVISED JULY 1995

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2.3	3.6	V
V	Library Company of the con-	V _{CC} = 2.3 V to 2.7 V	1.7		.,
V_{IH}	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		V
V	Law law Law Law Law Law	V _{CC} = 2.3 V to 2.7 V		0.7	
V_{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	Vcc	V
VO	Output voltage		0	Vcc	V
		V _{CC} = 2.3 V		-12	
lOH	High-level output current	V _{CC} = 2.7 V		-12	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 2.3 V		12	
lOL	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate		0	10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST COMPITIONS		., +	$T_A = -40^{\circ}C$ to $85^{\circ}C$			
PARAMETER	TEST CONI	DITIONS	v _{cc} †	MIN	TYP‡	MAX	UNIT
	I _{OH} = -100 μA		MIN to MAX	V _{CC} -0).2		
	$I_{OH} = -6 \text{ mA}$	V _{IH} = 1.7 V	2.3 V	2			
.,		V _{IH} = 1.7 V	2.3 V	1.7			.,
VOH	I _{OH} = -12 mA	V _{IH} = 2 V	2.7 V	2.2			V
		V _{IH} = 2 V	3 V	2.4			
	I _{OH} = -24 mA	V _{IH} = 2 V	3 V	2			
	I _{OL} = 100 μA		MIN to MAX			0.2	
	I _{OL} = 6 mA	V _{IL} = 0.7 V	2.3 V			0.4	
VOL	V _{IL} = 0.7 V		2.3 V			0.7	V
	$I_{OL} = 12 \text{ mA}$	V _{IL} = 0.8 V	2.7 V			0.4	
	I _{OL} = 24 mA	V _{IL} = 0.8 V	3 V			0.55	
II	V _I = V _{CC} or GND		3.6 V				μΑ
	V _I = 0.7 V			45			
	V _I = 1.7 V		2.3 V	-45			
I _{hold}	V _I = 0.8 V V _I = 2 V			75			μА
			3 V	-75			
	V _I = 0 to 3.6 V		3.6 V			±500	
loz§	V _O = V _{CC} or GND		3.6 V			±10	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ
ΔICC	V _{CC} = 3 V to 3.6 V, Other inputs at V _{CC} or GND	One input at V _{CC} – 0.6 V,				750	μΑ
C _i Control inputs	V _I = V _{CC} or GND		3.3 V		4		pF
Cio A or B ports	$V_O = V_{CC}$ or GND		3.3 V		8		pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V _{CC} =		V _{CC} =	2.7 V	V _{CC} =		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	150	0	150	MHz	
	Deleg desettes	LE high	3.3		3.3		3.3		ns	
t _W	Pulse duration	CLK high or low	3.3		3.3		3.3			
		Data before CLK↑	2.2		2.1		1.7			
t _{su}	t _{SU} Setup time	Data before LE↓, CLK high	1.9		1.6		1.5		ns	
		Data before LE↓, CLK low	1.3		1.1		1		1	
4.	Hold time	Data after CLK↑	0.6		0.6		0.7			
t _h	noid time	Data after LE↓, CLK high or low	1.4		1.7		1.4		ns	

 $[\]ddagger$ All typical values are at VCC = 3.3 V. \S For I/O ports, the parameter IOZ includes the input leakage current.

SN74ALVC16501 **18-BIT UNIVERSAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCAS261A - JANUARY 1993 - REVISED JULY 1995

switching characteristics over recommended operating free-air temperature range, (unless otherwise noted) (see Figures 1 and 2) $\,$

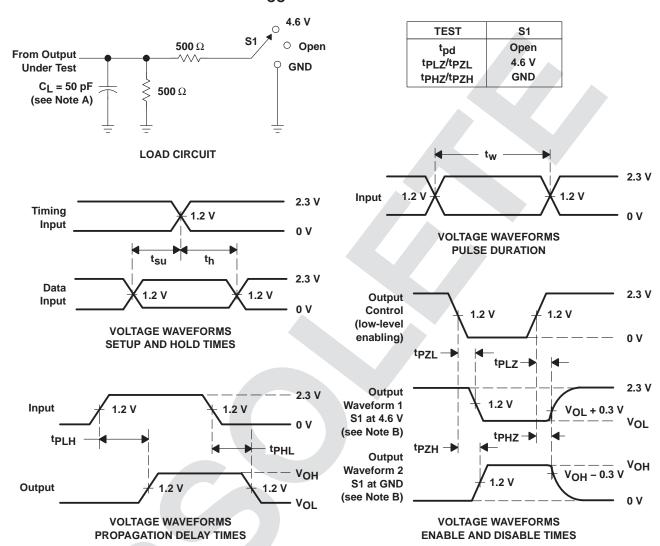
PARAMETER	FROM TO		V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 2.7 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
	(INPUT)	(OUTPUT)	MIN MAX	MIN MAX	MIN MAX	
f _{max}			150	150	150	ns
	A or B	B or A	1.2 5.4	4.5	1 3.9	
t _{pd}	LE	A or B	1.6 6.3	5.3	1.3 4.6	ns
·	CLK	A or B	1.7 6.7	5.6	1.4 4.9	
t _{en}	OEAB	В	1.1 6.3	5.3	1 4.6	ns
^t dis	OEAB	В	2.2 6.4	5.7	1.4 5	ns
t _{en}	OEBA	А	1.4 6.8	6	1.1 5	ns
^t dis	OEBA	А	2 5.5	4.6	1.3 4.2	ns

operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS		V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
					TYP	TYP	
C .	Power dissipation capacitance	Outputs enabled	C: - 50 pF	f = 10 MHz	44	54	pF
C _{pd}	Fower dissipation capacitance	Outputs disabled	$C_L = 50 \text{ pF},$	I = 10 WIHZ	6	6	ρг



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V

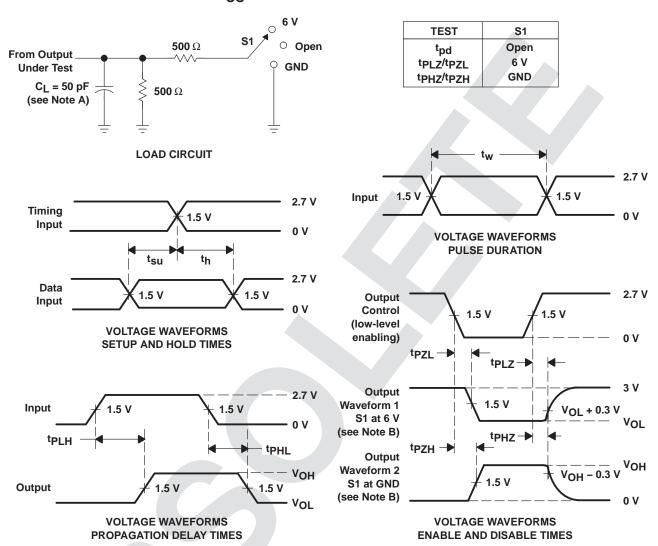


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





ti.com 24-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALVC16501DL	OBSOLETE	SSOP	DL	56	TBD	Call TI	Call TI
SN74ALVC16501DLR	OBSOLETE	SSOP	DL	56	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

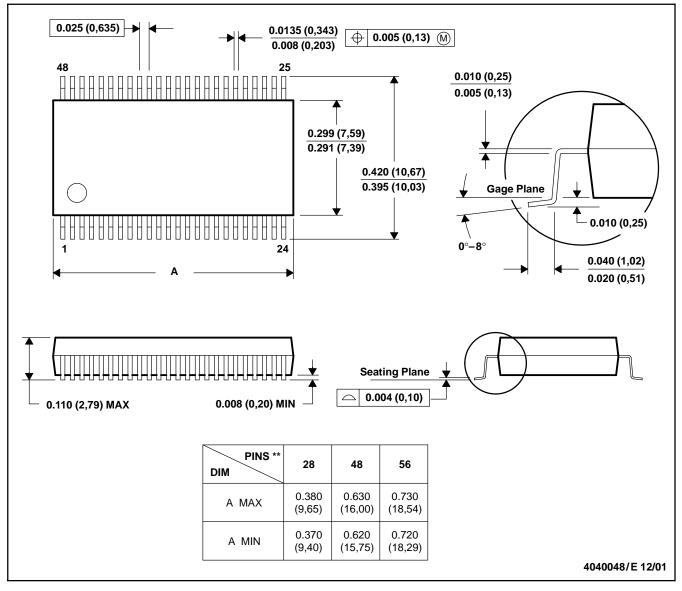
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mamt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated